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POWER SUPPLIES

PVDD RANGE = 27-30V

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These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
**CABLE ASSEMBLIES**

Cable 1
Analog Input Cable
IDC50x18"

Digi-Key Part# H3CCS-5018G-ND
(Cable Assembly)

No Instructions for Cable Assembly

Assembled Cable
(Not To Scale)

IDC50

IDC20

IDC24

Cable 2
I2S-OUT
IDC20x18"

Digi-Key Part# H3CCS-2018G-ND (Cable Assembly)

No Instructions for Cable Assembly

Assembled Cable
(Not To Scale)

IDC50

IDC20

IDC24

Cable 3
I2S-IN
IDC20-24x18"

Digi-Key Part#s H3CCS-2018G-ND (Cbl Assy) HHKC24S-ND (IDC Connector)

Instructions for Cable Assembly
1. Cut One Connector Leaving Max Ribbon
2. Crimp 24 Pin IDC Connector To Open End, Aligning Pin1 to Pin1

Assembled Cable
(Not To Scale)

IDC20

IDC24

Cable 4
I2S-IN
IDC20-24x26"

Digi-Key Part#s H3CCS-2036G-ND (Cbl Assy) HHKC24S-ND (IDC Connector)

Instructions for Cable Assembly
1. Cut One Connector off, Cut Cable Length = 26"
2. Crimp 24 Pin IDC Connector To Open End, Aligning Pin1 to Pin1

Assembled Cable
(Not To Scale)

IDC20

IDC24

Cable 5
110V Power Cable
JST to Lugs

Digi-Key Part#s Q307-ND (IEC Power Module) COLORED HEAT SHRINK (Any Vendor) 18ga Alpha Wire, Series 3055 (Black, White and Green) 455-1186-ND (JST 5 Pin Shell) Shell Crimp Pins (TI Will Supply These)

Assembled Cable + Module
(Not To Scale)
(Pin Positioning Moved for Clarity)

Instructions for Cable Assembly

- Eyelets
- Heat Shrink
- Expose 1/2", Tin and Solder to Eyelets (Bend Exposed section in half, then thread thru Eyelet)
- 18 ga Wires
- Expose 1/4", Crimp to JST Lugs
- JST Crimp Lugs
- INSERT LUGS INTO SHELL

Assembled Cable + Module
(Not To Scale)

IEC Module 
(Top)

L = Line (Black)
N = Neutral (White)
G = Ground (Green)

JST Shell

BACK

L
G
N
6"

INSERT LUGS INTO SHELL

N L G


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